

PRODUCT SPECIFICATION

16*2 Characters COB LCD MODULE MODEL: LT-1602E1-601 Ver:1.1

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	CUSTOMER'S	S APPROVAL
CUSTOMER :		
SIG	NATURE:	DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWD	REVIEWD	Ву

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• This specification is subject to change without notice. Please contact LT or its representative before designing your product based on this specification.

Revision Status

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1. Features

The features of LCD are showed as follows

- : FSTN/Transflective/Positive * Display mode
- * Controller IC : UCI7066-01(English-Japanese)
- * Display format : 16X2 Characters
- * Interface Input Data : 4 bit or 8 bit MPU
- * Driving Method
- : 1/16Duty, 1/4Bias * Viewing Direction : 6 O'clock
- * Backlight

- : 2 LED/Side White
- *Sample NO. : C1602A4FSW6B-B6_02/20171013

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	122(W) x 44(H) x 13.3MAX (D)	mm
Viewing Area	99(W) x 25(H)	mm
Activity Display Area	94.84 (W) x 20(H)	mm
Character Font	5x8 Dots	-
Character Size	4.84(W)x9.66(H)	mm
Character Pitch	6(W)x10.34(H)	mm
Dot Size	0.92(W)x1.1(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	+7.0	V
Supply Voltage For LCD Drive	V _{LCD}	Vdd-15.0	VDD+0.3	V
Input Voltage	Vin	-0.3	VDD+0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

*. NOTE: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

lt	ltem		Test Condition	Min.	Тур.	Max.	Unit	
Logic supply Voltage		$V_{DD}-{ m Vss}$	Ta = 25 °C	-	5	-	V	
LCD	LCD Drive			-	4.5	-	V	
	"H" Level	rel V IH1	V IH1	VDD=5V±5%	0.7 V_{DD}	-	V_{DD}	V
Input Voltage	"L" Level	V IL1		-0.3	-	0.6	V	
Frame F	Frame Frequency			-	75	-	Hz	
Current C	onsumption	I _{DD}		-	1.6	-	mA	

3-3 BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF	Ta = 25 °C	-	-	34	mA
Power Dissipation	PD	Ta = 25 C	-	-	153	mW
Reverse Current	IR	VR=5.0V/LED	-	-	1	uA

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	m	in	Ţ	ур	М	ax	Unit
Forward Current	IF		-	-	2	24		-	mA
Average Luminous Intensity	Lv	Vf=4.5V Ta = 25 °C	17	70	-		-		cd/m ²
Colour coordonate	-	14 20 0	X 0.25	Y 0.25	X 0.28	Y 0.28	X 0.32	Y 0.32	-

The brightness is measured without LCD panel

For operation above 25 °C, The Ifm & Pd must be derated, the current derating is -0.36mA/ °C for DC drive and -0.86mA/ °C for Pulse drive, the Power dissipation is -0.75mW/ °C. The product working current must not more than the 60% of the Ifm or Ifp according to the working temperature. Backlight lifetime means luminance value larger than half of the original after 20000 hours'

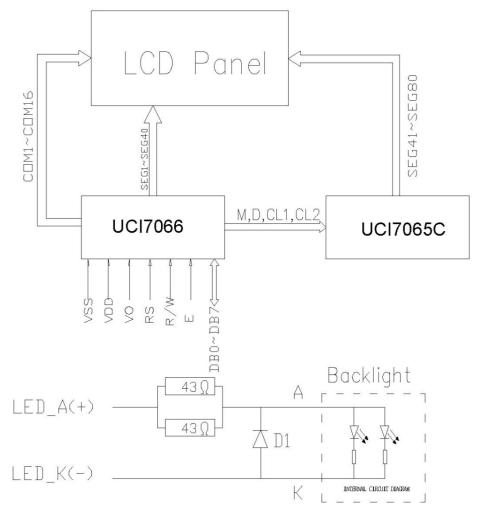
Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

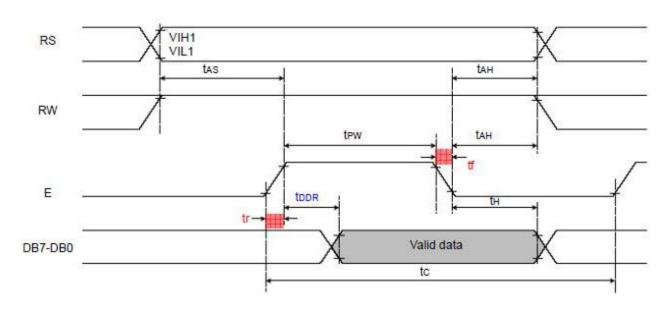
PIN NO.	SYMBOL	FUNCTIONS
1	LED_K	Backlight(0V)
2	LED_A	Backlight(+5V)
3	VSS	Ground
4	VDD	Supply voltage for logical circuit
5	V0	Supply voltage for LCD driving
6	RS	A signal for selecting registers. 1: Data Register (for read and write) 0: Instruction Register (for write)
7	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
8	Е	A enable signal for reading or writing data.
9~16	DB0~DB7	8 Bit Data Bus

4-2 BLOCK DIAGRAM

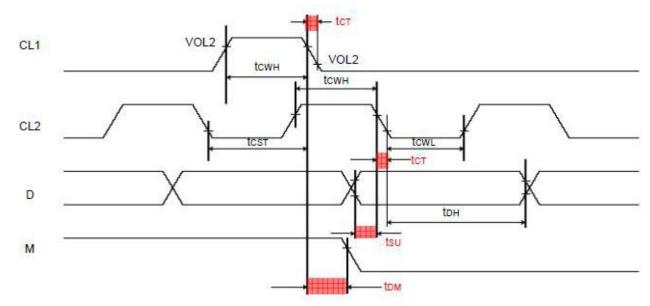


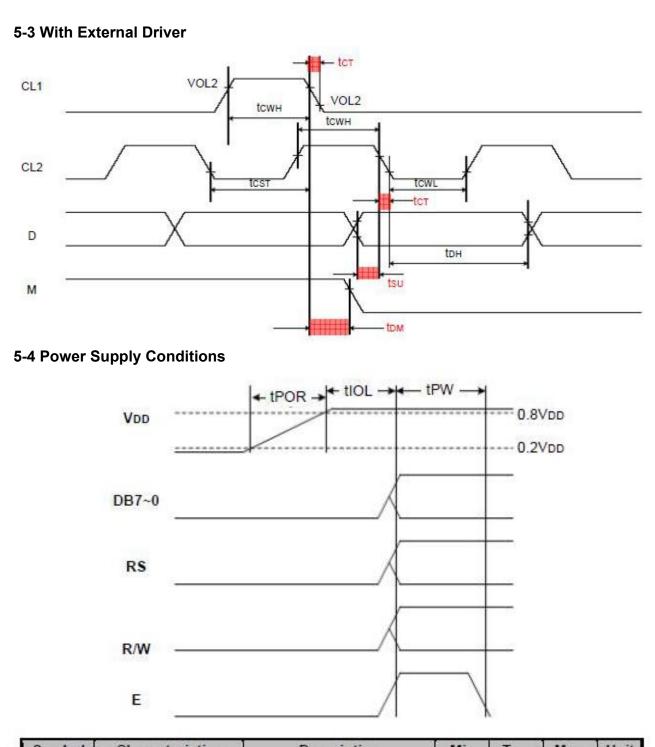
5. TIMING CHARACTERISTICS

5-1 Reading data from UCI7066U to MPU



5-2 Writing data from MPU to UCI7066U





Symbol	Characteristics	Description	Min	Тур.	Max.	Unit
tPOR	Power Rise time	Power rise time that will trigger internal POR circuit	0.1		100	mS
tIOL	I/O Low time	The period that I/O is kept LOW	40			mS
tPW	Enable Pulse width	Please refer to the following	tables	10 D		

5-5 Parameter

TA = 25°C, Vcc=4.5V~5V

Symbol	Characteristic	Test Condition	Min.	Тур.	Max.	Unit
Internal Cloc	k Operation		22			
fosc	OSC Frequency	R=91KΩ	190	270	350	KHz
External Cloc	ck Operation					
fex	External Frequency		125	270	410	KHz
	Duty Cycle	-	45	50	55	%
tR, tF	Rising/Falling Time	-	14	22	0.2	uS
Write Mode (MPU writes data to UCi7066)				88 40	20 20
tc	Enable Cycle Time	Pin E	1200	-	-	nS
tpw	Enable Pulse Width	Pin E	140	-	-	nS
tr, tr	Rising/Falling Time	Pin E	100		25	nS
tas	Address Setup Time	Pin: RS, RW, E	0	-	-	nS
tah	Address Hold Time	Pin: RS, RW, E	10	87	-	nS
tosw	Data Setup Time	Pin: DB7~DB0	40	-	-	nS
tH	Data Hold Time	Pin: DB7~DB0	10	57	-	nS
Read Mode (I	MPU reads data from UCi706	6)			ia ia	10 12
tc	Enable Cycle Time	Pin E	1200	-	-	nS
tpw	Enable Pulse Width	Pin <mark>E</mark>	140	-	-	nS
tR, tF	Rising/Falling Time	Pin E	-	1	25	nS
tas	Address Setup Time	Pin: RS, RW, E	0	-	-	nS
tan	Address Hold Time	Pin: RS, RW, E	10	-		nS
t DDR	Data Setup Time	Pin: DB7~DB0	-	-	100	nS
tн	Data Hold Time	Pin: DB7~DB0	10	-	=	nS
Interface Mod	de with LCD Driver (UCi7065)				
tсwн	Clock Pulse Width, High	Pin: CL1, CL2	800	-	Ŧ	nS
tcwL	Clock Pulse Width, Low	Pin: CL1, CL2	800	-	-	nS
tcst	Clock Setup Time	Pin: CL1, CL2	500			nS
tsu	Data Setup Time	Pin: D	300	822	-	nS
tDH .	Data Hold Time	Pin: D	300		-	nS
tom	M Delay Time	Pin: M	0	022	2000	nS

6. COMMAND LIST

#	Command	RS	R/W	D7	D6	D5	D4	D3	D2	D1	D0	Action
1	Clear Display	0	0	0	0	0	0	0	0	0	1	Clear the screen
2	Return Home	0	0	0	0	0	0	0	0	1	j.	Move cursor to HOME
3	Set Entry Mode	0	0	0	0	0	0	0	1	I/D	S	I/D: Left / Right S: Shift OFF/ON
4	Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D: Display OFF / ON C: Cursor OFF / ON B: Blink OFF / ON
5	Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L		23	S/C: Screen / Cursor R/L Right / Left
6	Set Function	0	0	0	0	1	DL	N	F			DL: 4-bit / 8-bit, N: 1-line / 2-line F: 5x8 / 5x11
7	Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	1011 - 1011 - 1011 - 101
8	Set DDRAM address	0	0	1	AC12	AC11	AC10	AC9	AC8	AC7	AC6	
9	Read Busy Flag and address	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	
10	Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data to RAM
11	Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from RAM
					For	\$8/\$9	Mode					
12	Status Read		1	0	0	0	0	0	0	0	0	Read status
12	Status Read	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	

Note:

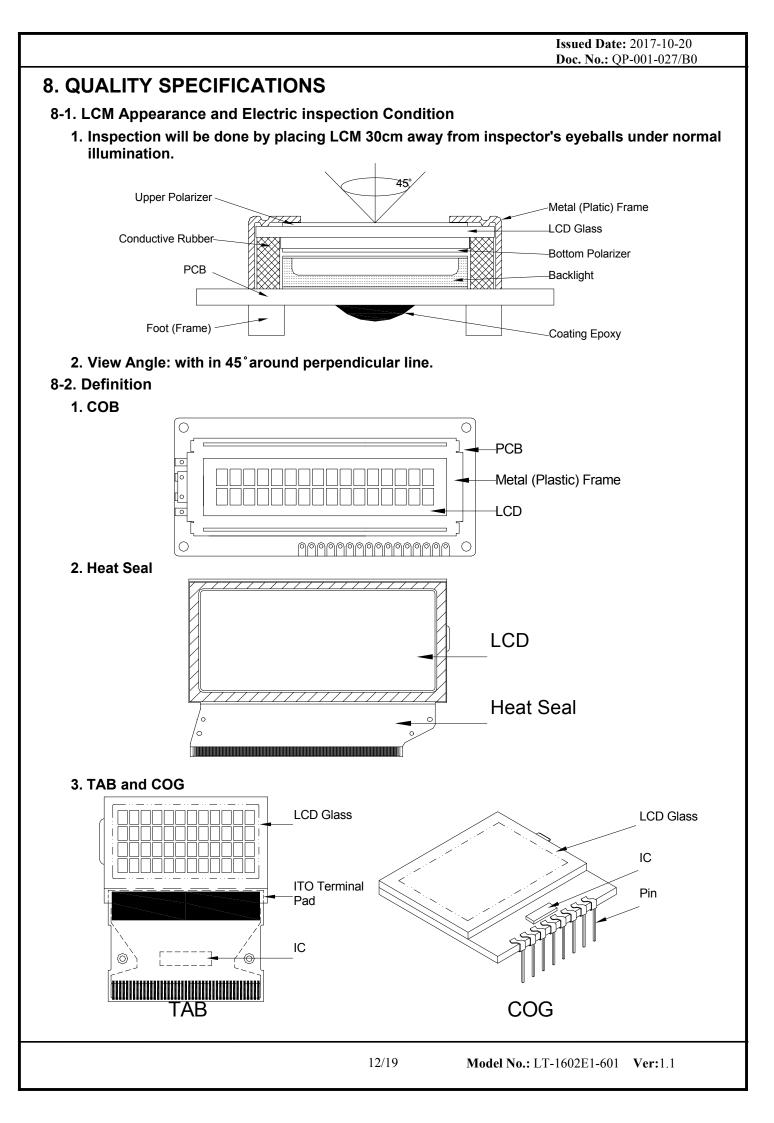
Ensure that UCi7066 is not in the BUSY state (BF = 0) before sending an instruction from the MPU to the UCi7066. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

7.CHARACTER GENERATOR ROM

Correspondence	between Character	Codes and Character	Patterns (ROM	Code: 0A)
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No. 7066-01

Upper 4 bits Lower 4 bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																
0001				1							D					
0010																
0011			H													•
0100				4				ł.				Т				
0101												-1				
0110			8								2					2
0111						IJ					7	Ŧ				
1000			Ľ	8										ļ		
1001												T			ITTE I	
1010											I					
1011						L										
1100											12					F
1101																
1110											-					
1111																



8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (\parallel) ordinary single inspection is used.

- 2.Acceptance
- Major defect:AQL = 0.65%Minor defect:AQL = 1.5%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift x component soldering pad x \rightarrow x \rightarrow x \rightarrow y	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component D Soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD PCB	<i>θ</i> ≤ 20°	Reject

3. Metal (Plast	tic) Frame						
Defect	Inspection Item	Ir	spection Standar	ds			
Major	Crack / breakage	Any	where	Reject			
		W	L	Acceptable of Scratch			
		w<0.1mm	Any	Ignore			
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2			
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1			
		w <u>></u> 0.3mm	Any	0			
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ <u><</u>	2				
	Frame Dent , Prick	1.0<	o <u><</u> 1.5mm	1			
Minor	$\Phi = \frac{L + W}{1 + W}$	1.5r	0				
	2	Note : 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored					
Minor	Frame Deformation	Excee	d the dimension of	drawing			
Minor	Metal Frame Oxidation		Any rust				

4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standa	rds
Minor	Tilte	d soldering	Within the angle +5°	Acceptable
Minor	Uneven s	older joint /bump		Reject
			Expose the conductive line	Reject
Minor	Hole	$\Phi = \frac{L + W}{2}$	⊕ > 1.0mm	Reject
Minor	, <u>⊀</u>	Distion shift $\rightarrow Z_{\leftarrow} - \psi_{-}$	Y > 1/3D	Reject
MILIO			X > 1/2Z	Reject

5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal TCP FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ > 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $Y \rightarrow Z \leftarrow V$ $Y \rightarrow Z \leftarrow V$ $Y \rightarrow Z \leftarrow V$	Y > 1/3D	Reject
WIITIO		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		⊕ ≤ 0.10mm	Ignore			
		0.10<⊕ <u><</u> 0.15mm	2			
Minor	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1			
		⊕>0.2mm	0			
		The distance between any two spots should be <u>></u> 5mm Any spot/dot/void outside of viewing area is acceptable				
Minor	Protective film tilt	Not fully cover LCD				
Major	COG coating	Not fully cover ITO circuit	Reject			

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

Defect	Insp	ect Item			Ins	spectio	n Si	tandards	5		
	•		W			0.03		03 <w<u><0.0</w<u>	5 V	V>0.05	
		* Glass Scratch* Polarizer Scratch	L			<5		L<3		Any	
Minor	Linear Defect	* Fiber and Linear	ACC. NO.			1		1		Reject	
		material	Note	L is the length and W is the width of the defec					fect		
		* Foreign material		Φ≤		0.1<⊕ <u><</u> (0.15	0.15<⊕ <u><</u> 0	.2	⊕>0.2	
	Black Spot and			3E/ 100n		2		1		0	
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	INOTE	Φ is the average diameter of the defect. Distance between two defects > 10mm.							
		* Unobvious	Φ		Φ <u><</u>	0.3	0.3	<@ <u><</u> 0.5	0.	5< Φ	
	White Spot	transparant foreign material between	NO.	3EA	A / 10	00mm²		1		0	
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note			-		er of the de fects > 10n			
			Φ	Φ <u><</u> 0	.10	0.10<⊕	<u><</u> 0.20	0.20<Φ <u>·</u>	<u><</u> 0.25	Φ >0 .	
	Segment Defect			ACC. NO.	3EA 100m		2		1		0
Minor				W is r	nore	than 1/2	segme	ent width		Reje	
			Note		$= \frac{L + W}{2}$				m		
			Φ	⊕ <u><</u> 0	.10	0.10<⊕	<u><</u> 0.20	0.20 <Φ	<u><</u> 0.25	Φ >0 .	
	Protuberant	w w	w	Glu	ie	W <u>≤</u> 1/2 W <u>≤</u> 0		W <u><</u> 1/2 W <u><</u> 0		Igno	
Minor	Segment	Φ = (L + W) / 2	ACC. NO.	3EA / 100mm ² 2			1		0		
			1. Segment						•		
			E			0.4mm		B <u><</u> 1.0mm -A<0.2		1.0mm <0.25	
Minor	Assembly Mis-alignment		Juc					ceptable		eptabl	
	<u>-</u>	- 2º Mar	2. Dot Matrix								
								Reje			
Minor	Stain on LCD Panel Surface		ora	similar	one	e. Otherw	/ise, j	ed lightly w judged ac /hite Spot"			

9. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	60℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: \pm 8KV 150pF/330 Ω 5 times	2	GB/T17626. 2 -2006
		Contact: ± 4 KV 150pF/330 Ω 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

- (2) Caution of LCD handling & cleaning
 - When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly. Isopropyl alcohol
 - Ethyl alcohol
 - Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone

- Aromatics

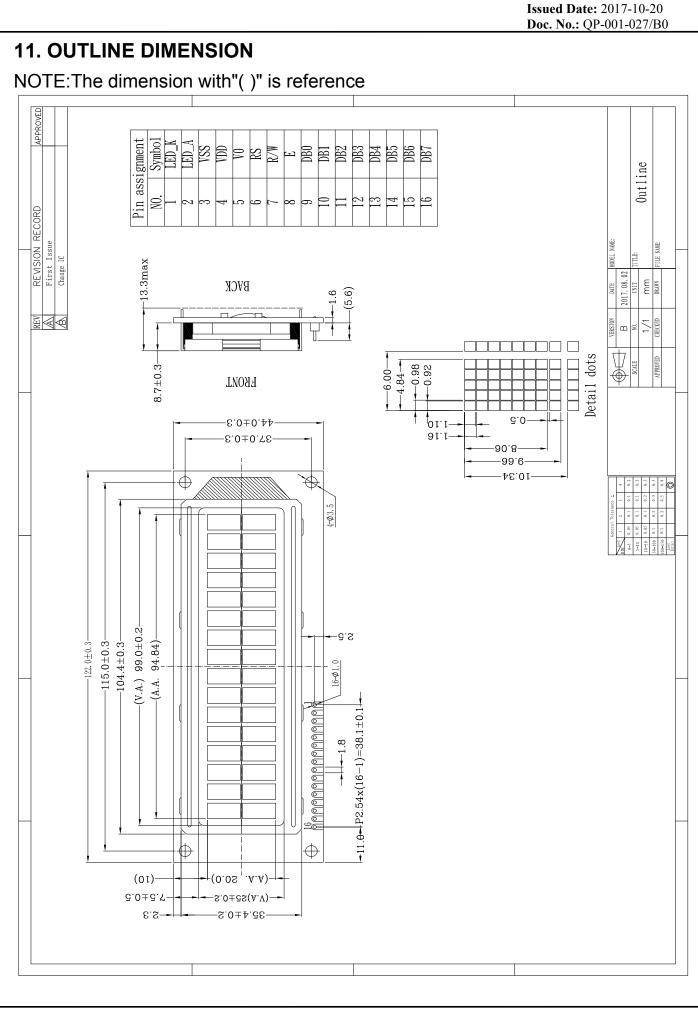
(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
 - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
 - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or
 - high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
 - Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
 - If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
 - A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

- In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
 - Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.
- (8) Other
 - After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.



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